

## METHOD FOR DETACHING SEMICONDUCTOR CHIPS FROM A FOIL

### ABSTRACT

The invention relates to the prepeeling phase of methods for detaching a semiconductor chip from the foil. In accordance with a first aspect, the invention relates to the determination of time  
5 periods, which each defines a duration of a prepeeling step, in which firstly at least one region of the semiconductor chip remains stucked to the foil and is bent and afterwards detaches from the foil. In a setup phase, the following steps are carried out for each prepeeling step:

Initiating the method step;

Repeating the two steps

- 10      Recording of an image of the semiconductor chip and assignment of a time period to the image which has passed since the initiation of the prepeeling step, and  
         Checking whether in the image a peripheral region of the semiconductor chip is darker than a predetermined brightness value;  
until the check leads to the result that no peripheral region of the semiconductor chip is darker  
15 than the predetermined brightness value.

In accordance with a second aspect, the invention relates to a method in which the detachment of the semiconductor chip from the foil is monitored in realtime.

Figure 4